WHAT IS CLAIMED IS:

1. A method of manufacturing an electromagnetic wave shielding filter, the method comprising:

preparing a metal plate for plating;

forming an insulating layer on an upper surface of the metal plate, the insulating layer having a mesh pattern;

forming a plating layer on a remaining upper surface of the metal plate on which the insulating layer is not formed;

arranging an adhesive film on the metal plate having the insulating layer and the plating layer;

adhering the adhesive film to upper surfaces of the insulating layer and the plating layer; and

separating the adhesive film from the metal plate so that the plating layer is adhered to a lower surface of the adhesive film, the plating layer being in the form of a mesh.

2. The method according to claim 1, wherein the metal plate comprises an alloy selected from at least one of SUS, a titanium alloy, a nickel alloy, a copper alloy, and an iron alloy, the metal plate acting as a seed layer for electrolytic plating.

3. The method according to claim 1, wherein the insulating layer is formed by oxide

coating.

4. The method according to claim 1, wherein the plating layer comprises at least one of copper or silver.

5. The method according to claim 1, wherein the adhesive film comprises polyethylene terephthalate (PET).

6. The method according to claim 1, wherein the adhesive film comprises a polymer film.

7. The method according to claim 1, wherein a binding force of the plating layer to the adhesive film is stronger than a binding force of the plating layer to the metal plate.

8. A method of manufacturing an electromagnetic wave shielding filter, the method comprising:

preparing a metal plate for plating;

forming a photoresist layer on an upper surface of the metal plate, the photoresist layer having a mesh pattern;

forming a plating layer on a remaining upper surface of the metal plate on which the photoresist layer is not formed;

removing the photoresist layer from the metal plate;

arranging an adhesive film on the metal plate having the plating layer;

adhering the adhesive film to an upper surface of the plating layer; and

separating the adhesive film from the metal plate so that the plating layer is adhered to a lower surface of the adhesive film, the plating layer being in the form of a mesh.

9. The method according to claim 8, wherein the metal plate comprises an alloy selected from at least one of SUS, a titanium alloy, a nickel alloy, a copper alloy, and an iron alloy, the metal plate acting as a seed layer for electrolytic plating.

10. The method according to claim 8, wherein the adhesive film comprises a polymer film.

11. A method of manufacturing an electromagnetic wave shielding filter, the method comprising:

preparing a substrate;

adhering a metal foil to an upper surface of the substrate;

forming a photoresist layer on an upper surface of the metal foil, the photoresist layer having a mesh pattern;

forming a plating layer on a remaining upper surface of the metal foil on which the photoresist layer is not formed;

removing the photoresist layer from the metal foil;

arranging an adhesive film on the metal foil having the plating layer;

adhering the adhesive film to an upper surface of the plating layer; and

separating the adhesive film from the metal foil so that the plating layer is adhered to a lower surface of the adhesive film, the plating layer being in the form of a mesh.

12. The method according to claim11, wherein the metal plate comprises an alloy selected from at least one of SUS, a titanium alloy, a nickel alloy, a copper alloy, and an iron alloy, the metal plate acting as a seed layer for electrolytic plating.

13. The method according to claim 11, wherein the plating layer comprises at least one of copper or silver.

14. The method according to claim 11, further comprising blackening the surface of the plating layer to increase contrast, after forming the plating layer.

15. The method according to claim 11, wherein the adhesive film comprises PET.

16. The method according to claim 11, wherein a binding force of the plating layer to the adhesive film is stronger than a binding force of the plating layer to the substrate or the metal foil.

17. The method according to claim 11, wherein the adhesive film comprises a polymer film.

18. An electromagnetic wave shielding filter, manufactured by preparing a substrate, forming a meshed plating layer on an upper surface of the substrate, adhering an adhesive film to an upper surface of the plating layer, and separating the adhesive film from the substrate so that the plating layer is adhered to a lower surface of the adhesive film.

19. The electromagnetic wave shielding filter according to claim 18, wherein the substrate is a metal plate arranged to act as a seed layer for electrolytic plating.

20. The electromagnetic wave shielding filter according to claim 18, wherein the metal plate comprises an alloy selected from at least one of SUS, a titanium alloy, a nickel alloy, a copper alloy, or an iron alloy.

21. The electromagnetic wave shielding filter according to claim 18, wherein the plating layer comprises at least one of copper or silver.

22. The electromagnetic wave shielding filter according to claim 18, wherein the surface of the plating layer is blackened.

23. The electromagnetic wave shielding filter according to claim 18, wherein the adhesive film comprises PET.

24. The electromagnetic wave shielding filter according to claim 18, wherein the adhesive film comprises a polymer film.

25. The electromagnetic wave shielding filter according to claim 18, wherein a transparent layer containing an acrylic solid is further arranged on the upper surface of the meshed plating layer to cover voids in the meshed plating layer.

26. The electromagnetic wave shielding filter according to claim 25, wherein the transparent layer comprises at least one of an acrylate or a butyl carbitol.

27. The electromagnetic wave shielding filter according to claim 25, wherein the transparent layer comprises 10% or less of an adhesive.